ASSOCIATION CONNECTING
ELECTRONICS INDUSTRIES ®

IPC-2252

Design Guide for RF/ Microwave Circuit Boards

IPC-2252
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A standard developed by IPC

Supersedes IPC-D-316
June 1995

2215 Sanders Road, Northbrook, IL 60062-6135
Tel. 847.509.9700 Fax 847.509.9798
www.ipc.org

The Principles of Standardization

In May 1995 the IPC's Technical Activities Executive Committee adopted Principles of Standardization as a guiding principle of IPC's standardization efforts.

Standards Should:

- Show relationship to Design for Manufacturability (DFM) and Design for the Environment (DFE)
- Minimize time to market
- Contain simple (simplified) language
- Just include spec information
- Focus on end product performance
- Include a feedback system on use and problems for future improvement

Standards Should Not:

- Inhibit innovation
- Increase time-to-market
- Keep people out
- Increase cycle time
- Tell you how to make something
- Contain anything that cannot be defended with data

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Adopted October 6. 1998

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Developed by the High Speed/High Frequency Design Task Group (D-21b) of the High Speed/High Frequency Committee (D-20) of IPC

Supersedes:
IPC-D-316 - June 1995

Users of this standard are encouraged to participate in the development of future revisions.

Contact:

IPC
2215 Sanders Road
Northbrook, Illinois
60062-6135
Tel 847 509.9700
Fax 847 509.9798

Acknowledgment

Any Standard involving a complex technology draws material from a vast number of sources. While the principal members of the High Speed/High Frequency Design Task Group (D-21b) of the High Speed/High Frequency Committee (D-20) are shown below, it is not possible to include all of those who assisted in the evolution of this standard. To each of them, the members of the IPC extend their gratitude.

High Speed/High Frequency Committee	**High Speed/High Frequency Design Task Group**	**Technical Liaison of the IPC Board of Directors**
Chair	Chair	
Tom Bresnan	Nicholas G. Paulter	William Beckenbaugh, Ph.D.
Kulicke & Soffa	NIST	Sanmina-SCI Corporation

High Speed/High Frequency Design Task Group

Amit Bhardwaj, Polar Instruments, Ltd.

Robert J. Black, Northrop Grumman Corporation

Ronald J. Brock, NSWC - Crane

John Bushie, Taconic, Advanced Dielectric Division

Byron Case, L-3 Communications

Christine R. Coapman, Delphi Delco Electronics Systems

Theodore Edwards, Dynaco Corporation

Werner Engelmaier, Engelmaier Associates, L.C.

Steven Fecanin, DuPont Engineering Polymers Automotive

Margie Hillsman, GE Transportation Systems

David H. Hoover, Multek

Thomas E. Kemp, Rockwell Collins

Roy M. Keen, Rockwell Collins

Robert J. Konsowitz, GIL Technologies

George T. Kotecki, Northrop Grumman Corporation

Cary Kyhl, Raytheon Systems Company

Roy Leventhal, CommWorks

Rene R. Martinez, TRW Electronics & Technology Division

Deepak K. Pai, C.I.D., Advanced Information Systems

John Reynolds, Rogers Corporation

Roberta Ross, Taconic Advanced Dielectric Division

Lowell Sherman, Defense Supply Center Columbus

G. Robert Traut, Rogers Corporation

Philip R Wellington, L-3 Communications

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